



SinglFuse™ SF-0603SP Series Features

- Time lag thin film chip fuse for overcurrent protection
- 1608 (EIA 0603) miniature footprint
- Surface mount packaging for automated assembly
- UL listed (UL 248-14)
- RoHS compliant* and halogen free**

SF-0603SP Series - Time Lag Surface Mount Fuses

Electrical Characteristics

Model	Rated Current (Amps)	Fusing Time	Resistance (mΩ) Typ.***	Rated Voltage	Breaking Capacity	Typical I ² t (A ² s) ****
SF-0603SP050	0.50	Open within 1~120 sec. at 200 % rated current	264	DC 50 V	DC 50 V 50 A	0.009
SF-0603SP063	0.63		200	DC 32 V	DC 32 V 50 A	0.014
SF-0603SP080	0.80		143			0.023
SF-0603SP100	1.00		83			0.036
SF-0603SP125	1.25		54			0.056
SF-0603SP150	1.50		42			0.081
SF-0603SP160	1.60		40			0.092
SF-0603SP200	2.00		28			0.145
SF-0603SP250	2.50		21.5			0.229
SF-0603SP300	3.00		18			0.332
SF-0603SP315	3.15		16			0.365
SF-0603SP400	4.00		13			0.574
SF-0603SP500	5.00		9.5			0.927
SF-0603SP600	6.00		6			1.860

*** Resistance value measured with less than 10 % of rated current. Tolerance ± 25 %.

****Typical I²t value measured at 10x rated current.

Reliability Testing

Parameter	Requirement	Test Method
Carrying Capacity	No fusing	Rated current, 4 hours
Fusing Time	Within 120 seconds	200 % of its rated current
Interrupting Ability	No mechanical damages	After the fuse is interrupted, rated voltage applied for 30 seconds again
Bending Test	No mechanical damages	Distance between holding points: 90 mm, Bending: 3 mm, 1 time, 30 seconds
Resistance to Solder Heat	± 20 %	260 °C ± 5 °C, 10 seconds ± 1 second
Solderability	95 % coverage minimum	235 °C ± 5 °C, 2 ± 0.5 second 245 °C ± 5 °C, 2 ± 0.5 second (lead free)
Temperature Rise	<75 °C	100 % of its rated current, measure of surface temperature
Resistance to Dry Heat	± 20 %	105 °C ± 5 °C, 1000 hours
Resistance to Solvent	No evident damage on protective coating and marking	23 °C ± 5 °C of isopropyl alcohol, 90 seconds
Residual Resistance	10k ohms or more	Measure DC resistance after fusing
Thermal Shock	$\Delta R < 10$ %	-20 °C / +25 °C / +125 °C / +25 °C, 10 cycles
UL File Number	E198545 http://www.ul.com/ Follow link to Online Certificates Directory, then enter UL File No. E198545, or click here	

Environmental Characteristics

Operating Temperature	-20 °C to +105 °C
Storage Conditions	
Temperature	+5 °C to +35 °C
Humidity	40 % to 75 %
Shelf Life	2 years from manufacturing date
Moisture Sensitivity Level	1
ESD Classification (HBM)	Class 6

* RoHS Directive 2015/863, Mar 31, 2015 and Annex.

**Bourns considers a product to be "halogen free" if (a) the Bromine (Br) content is 900 ppm or less; (b) the Chlorine (Cl) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (Cl) content is 1500 ppm or less. "SinglFuse" is a trademark of Bourns, Inc.

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

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SinglFuse™ SF-0603SP Series Applications

- Portable memory
- LCD monitors
- Disk drives
- PDAs
- Digital cameras
- DVDs
- Cell phones
- Rechargeable battery packs
- Battery chargers
- Set top boxes
- Industrial controllers

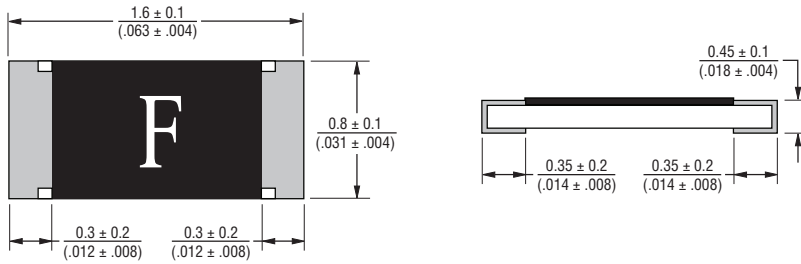
SF-0603SP Series - Time Lag Surface Mount Fuses **BOURNS®**

Solder Reflow Recommendations



PEAK: 250 +0/-5 °C, 5 seconds
PRE-HEATING ZONE: 150 to 180 °C, 90 ± 30 seconds
SOLDERING ZONE: 230 °C or higher, 30 ± 10 seconds

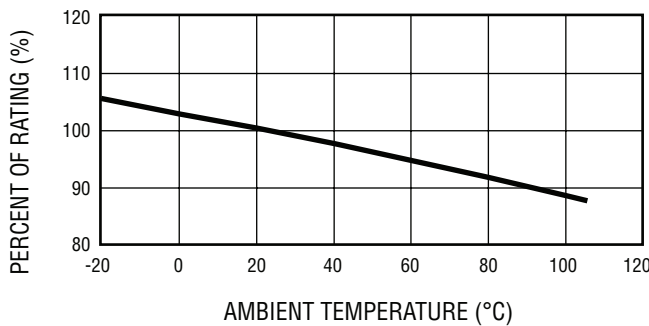
Product Dimensions



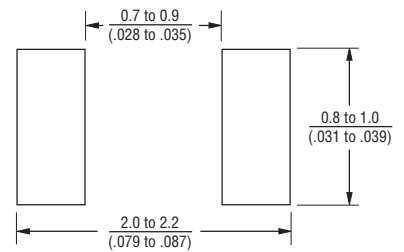
DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

PACKAGING: 5,000 pcs./reel

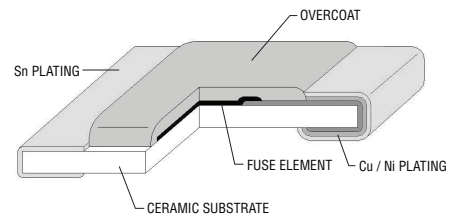
Thermal Derating Curve



Recommended Pad Layout



Construction & Material Content

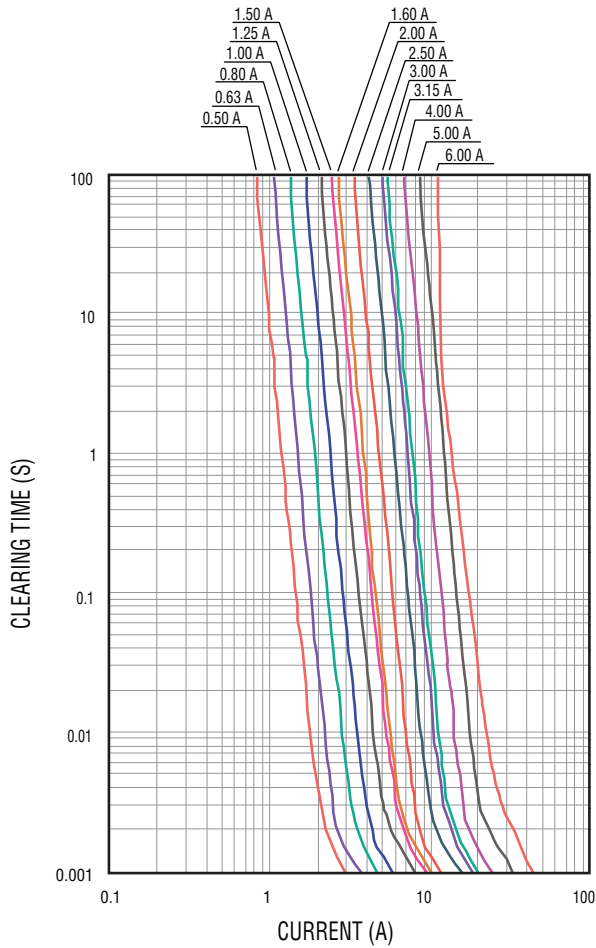


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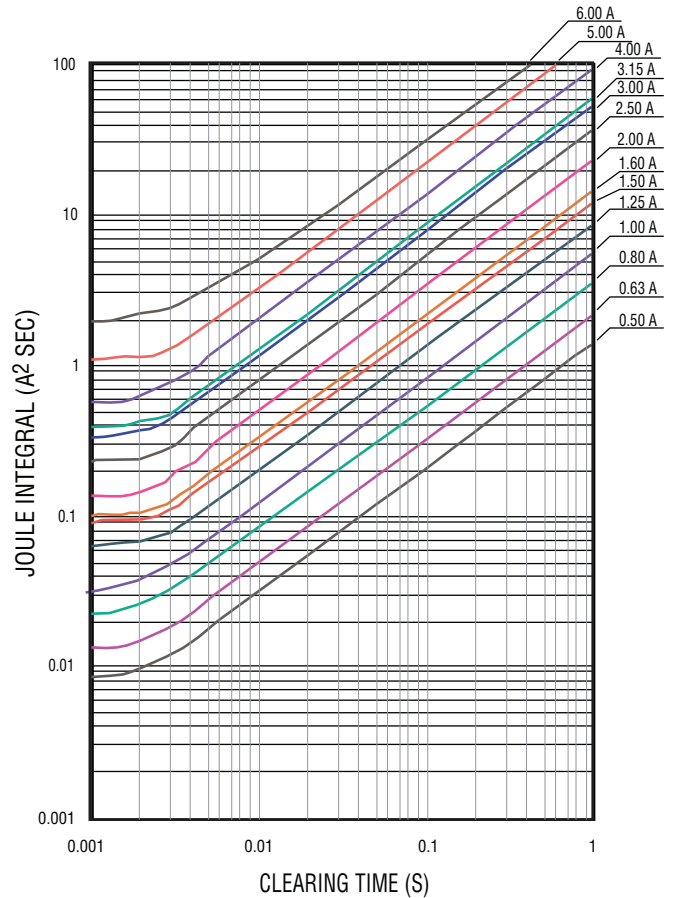
SF-0603SP Series - Time Lag Surface Mount Fuses



Average Time Current Curves



Minimum I²T V Clear Time Curves



Typical Part Marking

Represents total content. Layout may vary.



RATED CURRENT (A)	
F = 0.50	S = 2.00
I = 0.63	T = 2.50
K = 0.80	3 = 3.00
L = 1.00	U = 3.15
M = 1.25	W = 4.00
N = 1.60	Y = 5.00
P = 1.50	<u>6</u> = 6.00

How to Order

SF - 0603 SP 050 - 2

SinglFuse™
 Product Designator _____
 SMD Footprint
 1608 (EIA 0603) size
 Fuse Blow Type
 SP = Time lag
 Rated Current
 050-600 (500 mA - 6.00 A)
 Packaging Type
 - 2 = Tape & Reel (5,000 pcs./reel)

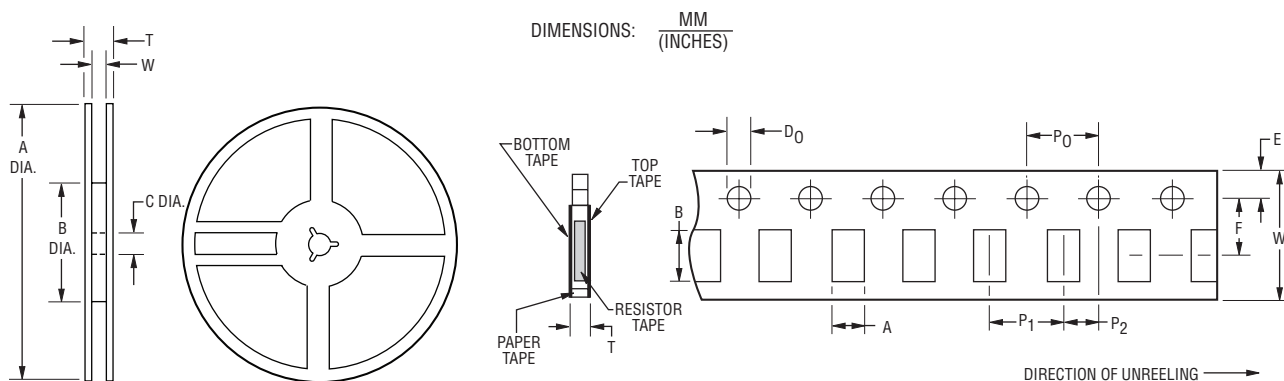
REV. B 09/17

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SF-0603SP Series Tape and Reel Specifications

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Tape Dimensions	SF-0603SP Series per EIA 481-2
W	$\frac{8.0 \pm 0.2}{(.315 \pm .008)}$
P ₀	$\frac{4.0 \pm 0.1}{(.157 \pm .004)}$
P ₁	$\frac{4.0 \pm 0.1}{(.157 \pm .004)}$
P ₂	$\frac{2.0 \pm 0.05}{(.079 \pm .002)}$
A	$\frac{1.1 \pm 0.1}{(.043 \pm .004)}$
B	$\frac{1.9 \pm 0.1}{(.075 \pm .004)}$
F	$\frac{3.5 \pm 0.05}{(.138 \pm .002)}$
E	$\frac{1.75 \pm 0.1}{(.069 \pm .004)}$
D ₀	$\frac{1.5 + 0.1/-0}{(.059 + .004/-0)}$
T	$\frac{0.64 \pm 0.1}{(.025 \pm .004)}$
Reel Dimensions	
A	$\frac{180 +0/-3.0}{(7.087 +0/-118)}$
B Min.	$\frac{60.0}{(2.362)}$
C	$\frac{13.0 \pm 1.0}{(.512 \pm .039)}$
W	$\frac{9.0 \pm 1.0}{(.354 \pm .039)}$
T	$\frac{11.4 \pm 2.0}{(.449 \pm .079)}$



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